DuPont™ EKC1020™ Negative Resist Remover

**Product Description**
DuPont™ EKC1020™ negative resist remover contains no phenol or chlorinated solvents and will remove photoresist without attack of conventional interconnect materials, copper, or polyimide films.

Typical applications for EKC1020™ include integrated circuits, backlap cleaning, chrome photomasks, etc. These products can also be used to remove epoxy inks and backlap way, acrylic adhesives as well as grease, oils and other organics from glassware.

DuPont™ EKC1020™ is specifically formulated to remove negative photoresist and to be compatible with sensitive metals where corrosion is a concern.

**Performance Characteristics**

**Strip Time and Temperature**
EKC1020™ strips negative and positive resist in 10 to 20 minutes under normal circumstances when heated to 105 °C ± 5 °C. For best results, two baths in sequence are preferred. The operating temperature of the stripper and process time may need to be adjusted to accommodate individual needs. Contact your DuPont EKC technical representative for specific process recommendations.

**Bath Life**
EKC1020™ typically lasts eight hours at elevated temperatures in an uncovered bath. Longer bath life can be achieved by covering the bath.

**High Wafer Throughput**
EKC1020™ will strip 700-1000 wafers per setup. Throughput will vary according to wafer size, resist thickness and percent of coverage.
For more information on DuPont™ EKC1020™ or other DuPont products, please visit our website.

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. It may be subject to revision as new knowledge and experience becomes available. This information is not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. Since we cannot anticipate all variations in end-use and disposal conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. It is intended for use by persons having technical skill, at their own discretion and risk. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.


DuPont™, the DuPont Oval Logo, and all products, unless otherwise noted, denoted with “™,” “®” or “SM” are trademarks, service marks or registered trademarks of affiliates of DuPont de Nemours, Inc. © 2019 DuPont de Nemours, Inc. All rights reserved.

K-10775-2 (06/19)